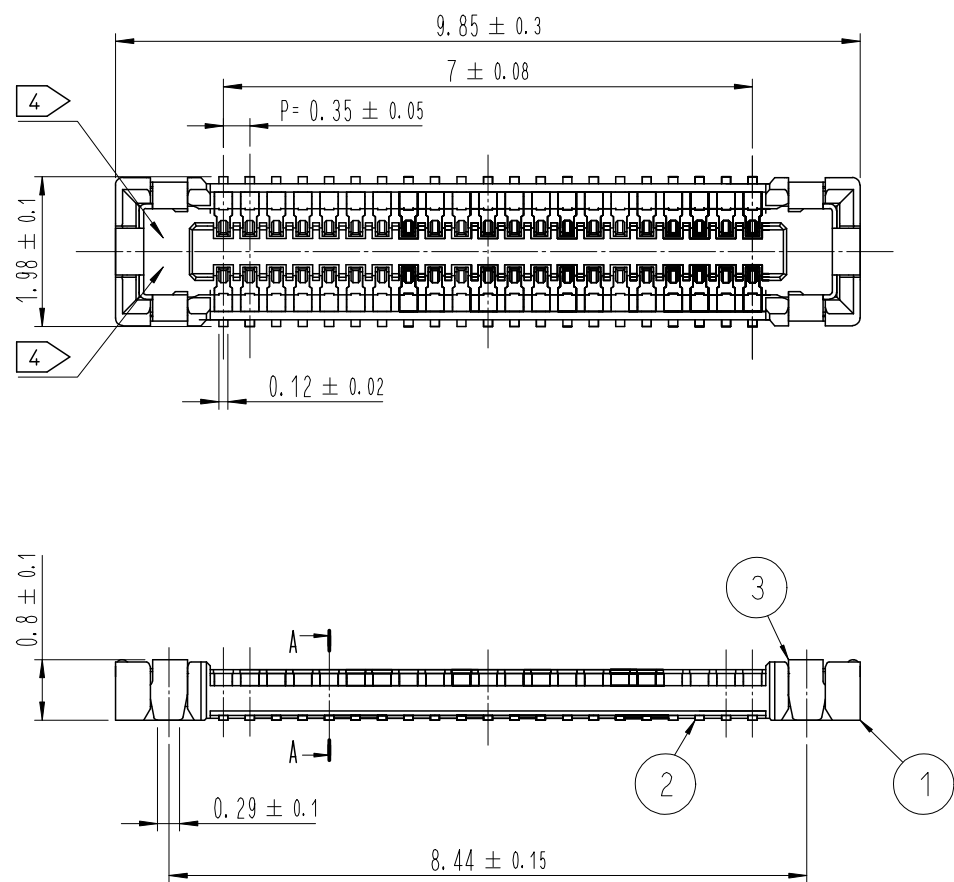


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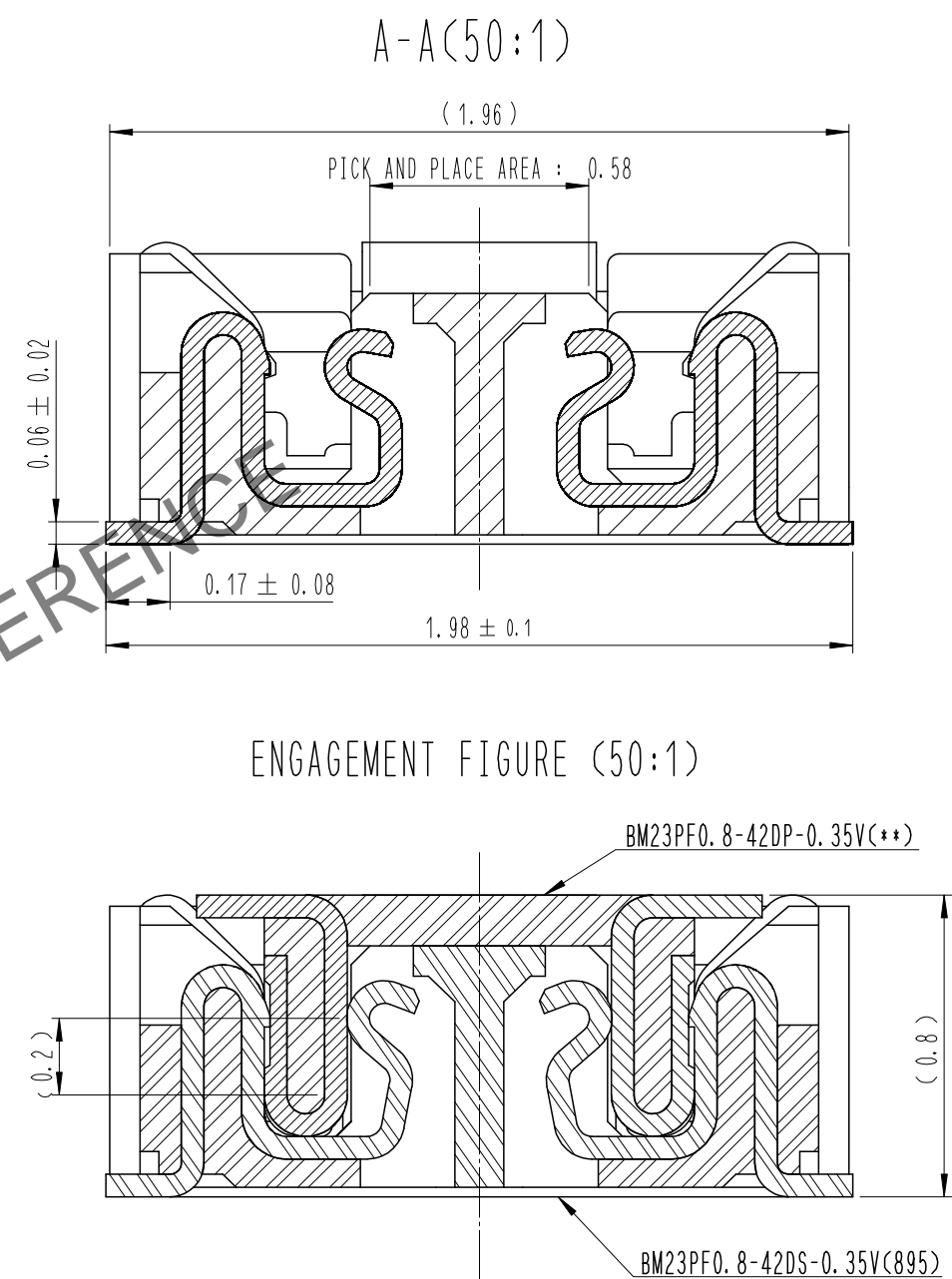
A
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DRAWING FOR REFERENCE
This is subject to change without notice

- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
 - 2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD $0.05\mu\text{m}$ MIN.
SMT LEAD : GOLD $0.05\mu\text{m}$ MIN.
UNDERPLATING : NICKEL $1\mu\text{m}$ MIN.
(SURFACE : SEALING)
 - 3. MATA FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD $0.05\mu\text{m}$ MIN.
UNDERPLATING : NICKEL $1\mu\text{m}$ MIN.
(SURFACE : SEALING)
 - 4. HRS MARK AND CAV NO. IS INDICATED IN APPROX POSITION SHOWN.

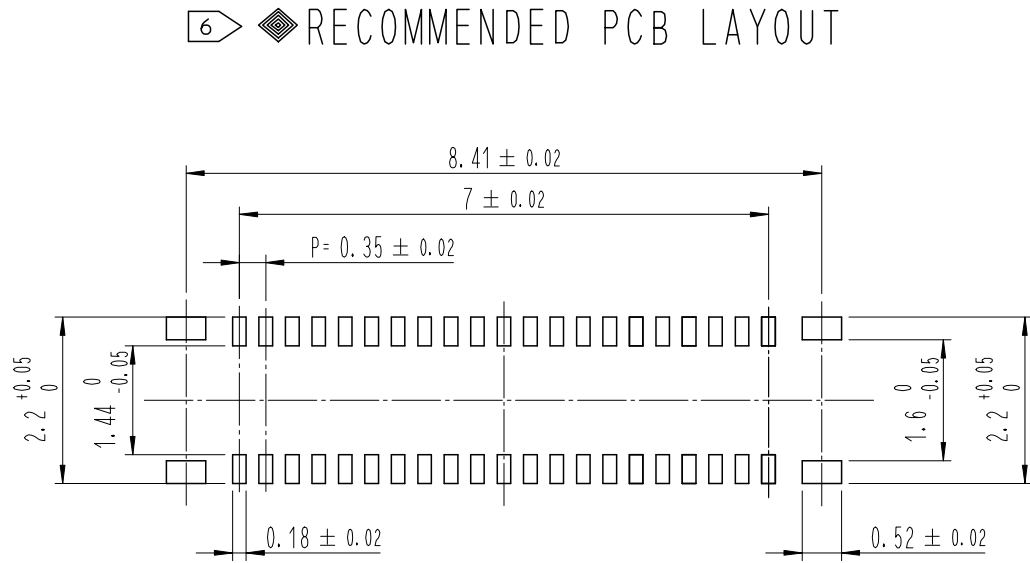
5		6			7			8			
	△數 COUNT	訂正事項 DESCRIPTION OF REVISIONS	擔當 B Y	檢圖 CHKD	年月日 DATE		△數 COUNT	訂正事項 DESCRIPTION OF REVISIONS	擔當 B Y	檢圖 CHKD	年月日 DATE
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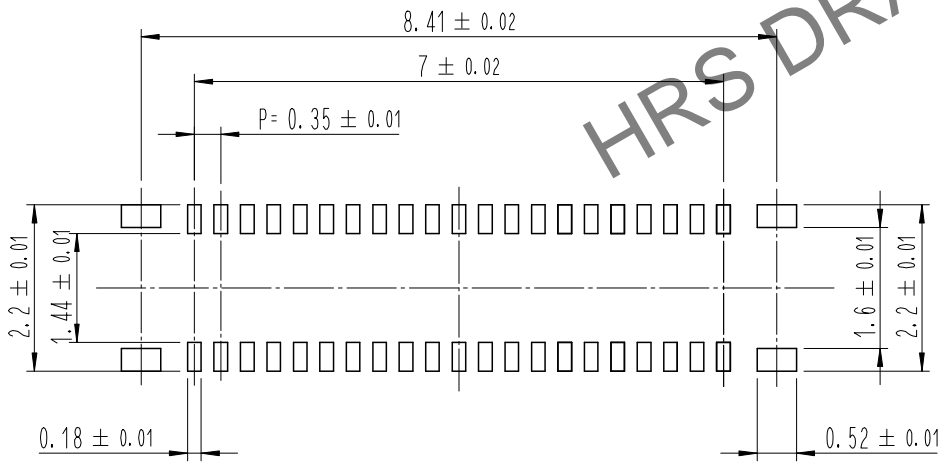
4	PS	CLEAR (EMBOSSED CARRIER TAPE)						
3	COPPER ALLOY	3						
2	COPPER ALLOY	2	6	PS	BLACK (PLASTIC REEL)			
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)			
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS			
REMARKS				DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
				S. H. JUNG	S. H. JUNG	H. W. JO	T. S. KANG	17. 05. 09
				17. 05. 09	17. 05. 09	17. 05. 09	17. 05. 09	
CODE NO. (OLD)		DRAWING NO.		PART NO.				
		EDC3-632163		BM23PF0.8-42DS-0.35V(895)				
SCALE		HRS HIROSE KOREA CO., LTD.		CODE NO				1 3
10:1								
UNITS				CL 6644-0081-6-895				
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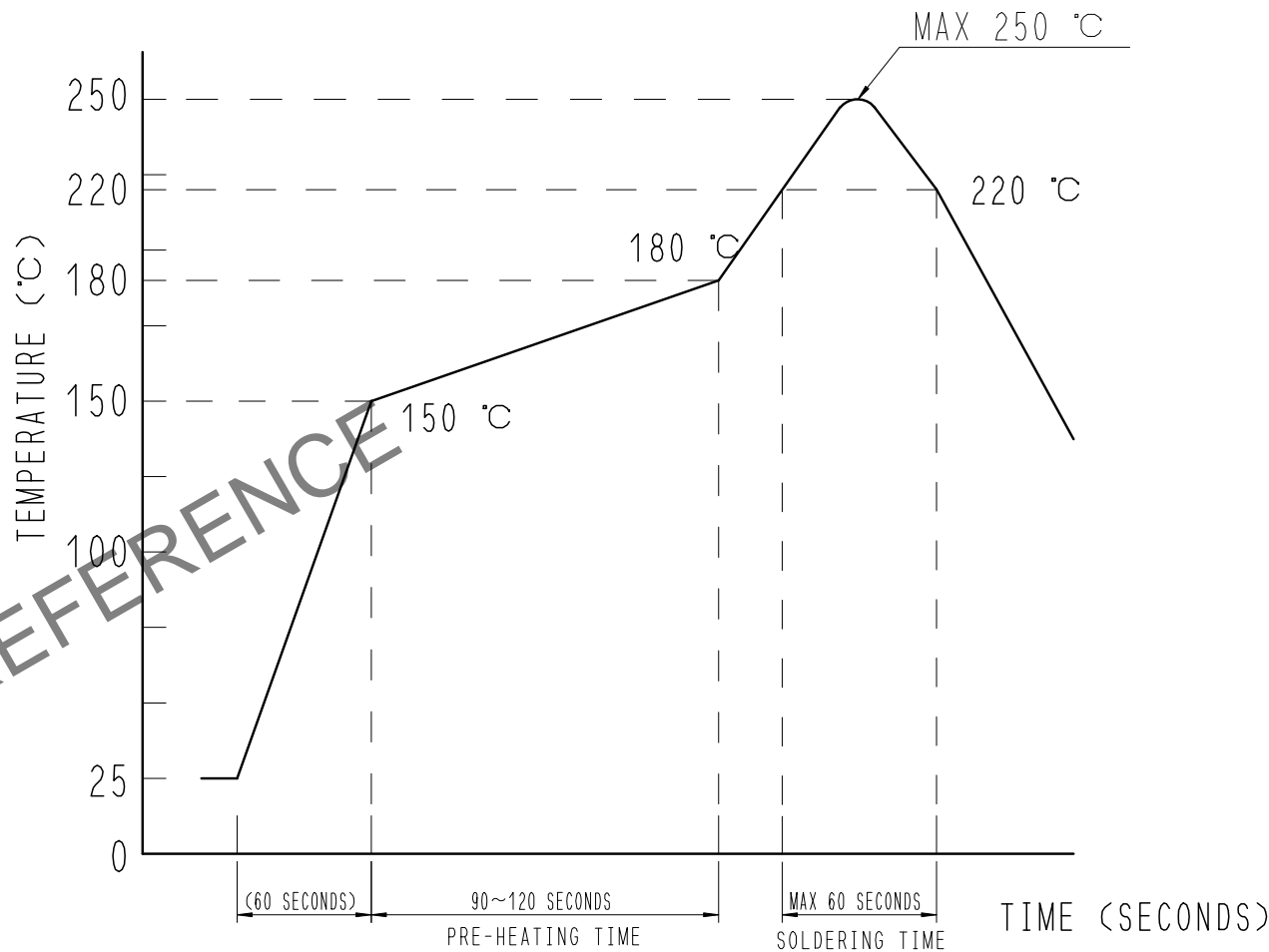
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RECOMMENDED METAL MASK DIMENSIONS
MATAL MASK THICKNESS : 100 μm



5 RECOMMENDED REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N2 REFLOW
NUMBER OF REFLOW CYCLES:2 CYCLES MAX.
1)REFLOW TIME
DURATION ABOVE 220°C, 60 SEC MAX.
(PEAK TEMPERATURE:250°C MAX)
2)PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN):150°C
PRE-HEAT TEMPERATURE(MAX):180°C
PRE-HEAT TIME:90-120 SEC.

- 5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 6 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-632163	PART NO.	BM23PF0.8-42DS-0.35V(895)
	SCALE	10:1	CODE NO	CL 6644-0081-6-895
	UNITS	mm		

HIROSE KOREA CO., LTD.

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